

## Wafer Cutting Apparatus (WCM)



The wire cutting machine "WCM" is manually operated and cuts wafer blocks to small wafer fingers of predetermined dimensions. The cutter frame and feed bar can be exchanged to produce other size of biscuits. The machine is used for cutting of small scale output.

### Technical Data

Machine Variables	WCM
Size of the Wafer (Possible)	270x370
Stack Height (mm)	10 to 70
Minimum Cutting Width (mm)	16
Cutting Wire (spring steel in mm)	0.5
Connected load (Kw)	—
<b>Dimensions (mm)</b>	
Length	1450
Width	1130
Height	675
Net weight (appx. Kgs)	110
Shipping volume (CBM)	1

## Wafer Creaming Apparatus (WCR)

It is a simple stenciling apparatus. The Sheet holder is designed to hold the sheet in place and allow desired cream application. A knife is used for depositing a layer of cream for sandwiching the wafer biscuits. The apparatus can be attended by an unskilled operator.



**Note : The above machines are of low scale manual operation.**

*Limited level of automation for cutting and creaming can be used in this manual process for better quality products.*

\* Modifications Reserved

**R&D Engineers**

A-41, IDA Kukatpally, Phase II, Road No.4, Via I.E. Gandhi Nagar, Hyderabad-500 037. India.  
Phone: 23079121, 23079878, Fax: 0091-40-23078668  
E-mail: info@rndwafers.com

Web: [www.rndwafers.com](http://www.rndwafers.com)

Local Contact :